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An integrated circuit package as in Claim 14, wherein said array of die attach pads and conductive dies is being arranged in a regular pattern so as to allow singulation of said integrated circuit packages by sawing through said plastic encapsulation and said conductive leads at predetermined positions.

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REMARKS

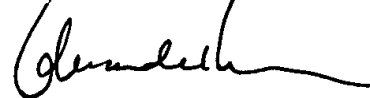
Claims 1-10 are canceled. Claims 11-17 are newly presented to more particularly point out and distinctly claim Applicants' invention.

If the Examiner has any questions regarding the above, the Examiner is respectfully requested to telephone the undersigned Attorney for Applicants at 408-453-9200.

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Respectfully submitted,



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